

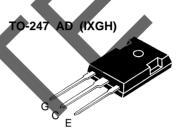
# $\begin{array}{c} \text{Low V}_{\text{CE(sat)}} \text{ IGBT} \\ \text{High speed IGBT} \end{array}$

#### 

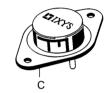


Symbol	<b>Test Conditions</b>	Maximum Ratings		
V <sub>ces</sub>	$T_J = 25$ °C to $150$ °C	1000	V	
$\mathbf{V}_{\mathtt{CGR}}$	$T_{_{ m J}}$ = 25°C to 150°C; $R_{_{ m GE}}$ = 1 M $\Omega$	1000	V	
V <sub>GES</sub>	Continuous	±20	V	
$V_{\rm GEM}$	Transient	±30	У	
I <sub>C25</sub>	T <sub>c</sub> = 25°C	34	А	
I <sub>C90</sub>	$T_c = 90^{\circ}C$	17	А	
I <sub>CM</sub>	$T_{\rm C}$ = 25°C, 1 ms	68	A	
SSOA (RBSOA)	$V_{GE}$ = 15 V, $T_{VJ}$ = 125°C, $R_{G}$ = 82 $\Omega$ Clamped inductive load, L = 300 $\mu$ H	$I_{CM} = 34$ @ 0.8 $V_{CES}$	A	
P <sub>c</sub>	T <sub>c</sub> = 25°C	150	W	
T <sub>J</sub>		-55 +150	°C	
T <sub>JM</sub>		150	°C	
T <sub>stg</sub>		-55 +150	°C	
M <sub>d</sub>	Mounting torque (M3)	1.13/10	Nm/lb.in.	
Weight		TO-204 = 18 g, TO-	-247 = 6 g	
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s				

#### **Test Conditions Characteristic Values Symbol** (T<sub>1</sub> = 25°C, unless otherwise specified) min. max. typ. $= 3 \text{ mA}, V_{GE} = 0 \text{ V}$ **BV**<sub>CES</sub> 1000 ٧ = 250 $\mu$ A, $V_{CE} = V_{GE}$ 2.5 5 V V<sub>GE(th)</sub> $V_{CE} = 0.8 \bullet V_{CES}$ $V_{GE} = 0 V$ T<sub>1</sub> = 25°C 250 μΑ I<sub>CES</sub> T<sub>1</sub> = 125°C 1 mΑ $V_{CE} = 0 \text{ V}, V_{GE} = \pm 20 \text{ V}$ ±100 nΑ I<sub>GES</sub> $I_{C} = I_{C90}, V_{GE} = 15 \text{ V}$ ٧ V<sub>CE(sat)</sub> 17N100 3.5 17N100A 4.0 ٧



# TO-204 AE (IXGM)



G = Gate, C = Collector, E = Emitter, TAB = Collector

### **Features**

- · International standard packages
- 2nd generation HDMOS<sup>™</sup> process
- Low  $\overline{V}_{CE(sat)}$
- for low on-state conduction losses
- · High current handling capability
- MOS Gate turn-on
  - drive simplicity
- Voltage rating guaranteed at high temperature (125°C)

# **Applications**

- AC motor speed control
- · DC servo and robot drives
- · DC choppers
- Uninterruptible power supplies (UPS)
- Switch-mode and resonant-mode power supplies

## **Advantages**

- Easy to mount with 1 screw (TO-247) (isolated mounting screw hole)
- · High power density



Symbol	Test Conditions Cha $(T_J = 25^{\circ}\text{C}, \text{ unless c} \text{min.})$	aracteriotherwis		
${f g}_{\sf fs}$	$I_{C} = I_{C90}$ ; $V_{CE} = 10 \text{ V}$ , 6 Pulse test, t $\leq$ 300 $\mu$ s, duty cycle $\leq$ 2 %	15		S
C <sub>ies</sub> C <sub>oes</sub> C <sub>res</sub>	$ V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz} $	1500 175 40		pF pF pF
Q <sub>g</sub> Q <sub>ge</sub> Q <sub>gc</sub>		100 20 60	120 30 90	nC nC nC
$\mathbf{t}_{d(on)}$ $\mathbf{t}_{ri}$ $\mathbf{t}_{d(off)}$ $\mathbf{t}_{fi}$ $\mathbf{E}_{off}$	Inductive load, $T_J = 25^{\circ}C$ $I_C = I_{C90}, V_{GE} = 15 \text{ V}, L = 300 \mu\text{H}, V_{CE} = 0.8 V_{CES}, R_G = R_{off} = 82 \Omega$ $Remarks: Switching times may increase for V_{CE} (Clamp) > 0.8 • V_{CES}, higher T_J or increased R_G 17N100A$	100 200 500 750 450 3	1000 750	ns ns ns ns ns ns
t <sub>d(on)</sub> t <sub>ri</sub> E <sub>on</sub> t <sub>d(off)</sub> t <sub>li</sub>	Inductive load, $T_J$ = 125°C $I_C = I_{C90}, V_{GE} = 15 \text{ V}, L = 300 \mu\text{H}$ $V_{CE} = 0.8 V_{CES}, R_G = R_{off} = 82 \Omega$ Remarks: Switching times may increase for $V_{CE}$ (Clamp) > 0.8 • $V_{CES}$ , higher $T_J$ or increased $R_G$ 17N100 17N100A	100 200 2.5 700 1200 750 8	1000 2000 1000	ns ns mJ ns ns ns mJ mJ
R <sub>thJC</sub>		0.25	0.83	K/W

IXGH 17N100 and IXGH 17N100 A characteristic curves are located on the IXGH 17N100U1 and IXGH 17N100AU1 data sheets.

